

CEC6P61

-60V ▲ 100mΩ ▲ -11A ▲ Si MOSFET

SILICON Si MOSFET ▲ SMD type

P-channel enhancement mode

UL94V-0 rated flame retardant epoxy

DFN3x3 package ▲ MSL 3

Super high dense cell density for extremely low $R_{DS(ON)}$

High power and current handling capability






MAXIMUM RATINGS

Parameter ($T_C = 25^\circ\text{C}$, unless otherwise noted)		Characteristics	
Drain-Source Voltage	V_{DS}	-60V	
Gate-Source Voltage	V_{GS}	$\pm 20\text{V}$	
Continuous Drain Current at R_{TH_JC}	I_D	-11A at $T_C = 25^\circ\text{C}$	-7A at $T_C = 100^\circ\text{C}$
Continuous Drain Current at R_{TH_JA}	I_D	-3.5A at $T_A = 25^\circ\text{C}$	-2A at $T_A = 100^\circ\text{C}$
Pulsed Drain Current at R_{TH_JC} ^{Note 1}	I_{DM}	-44A at $T_C = 25^\circ\text{C}$	
Pulsed Drain Current at R_{TH_JA} ^{Note 1}	I_{DM}	-14A at $T_A = 25^\circ\text{C}$	
Maximum Power Dissipation	P_D	25W at $T_C = 25^\circ\text{C}$	2.5W at $T_A = 25^\circ\text{C}$
Operating and Storage Temperature Range	T_J, T_{STG}	-55°C to $+150^\circ\text{C}$	

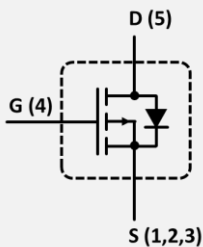
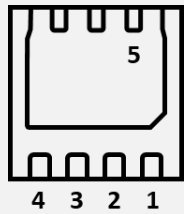
THERMAL CHARACTERISTICS

Parameter	Symbol	Limit
Thermal Resistance, Junction-to-Case ^{Note 2}	R_{TH_JC}	5°C/W
Thermal Resistance, Junction-to-Ambient ^{Note 2}	R_{TH_JA}	50°C/W

APPLICATIONS

DC/DC Converter	DC Fan	Load Switches	Power Banks	USB Storage
				

PIN DESCRIPTION

Circuit Diagram	Outline - Bottom View	Pin No.	Description
		1 2 3 4 5	Source Source Source Gate Drain

ELECTRICAL CHARACTERISTICS ▲ $T_A = 25^\circ\text{C}$, unless otherwise noted

Item	Condition	Symbol	Min.	Typ.	Max.	Unit
Off Characteristics						
Drain-Source Breakdown Voltage	$V_{GS} = 0V, I_D = -250\mu A$	BV_{DSS}	-60			V
Zero Gate Voltage Drain Current	$V_{DS} = -60V, V_{GS} = 0V$	I_{DSS}			-1	μA
Gate Body Leakage Current, Forward	$V_{GS} = 20V, V_{DS} = 0V$	I_{GSSF}			100	nA
Gate Body Leakage Current, Reverse	$V_{GS} = -20V, V_{DS} = 0V$	I_{GSSR}			-100	nA
On Characteristics ^{Note 3}						
Gate Threshold Voltage	$V_{GS} = V_{DS}, I_D = -250\mu A$	$V_{GS(th)}$	-1		-3	V
Static Drain-Source On-Resistance	$V_{GS} = -10V, I_D = -3A$	$R_{DS(ON)}$		100	125	m Ω
Static Drain-Source On-Resistance	$V_{GS} = -4.5V, I_D = -2A$	$R_{DS(ON)}$		120	170	m Ω
Dynamic Characteristics ^{Note 4}						
Input Capacitance	$V_{DS} = -30V, V_{GS} = 0V, f = 1MHz$	C_{ISS}		575		pF
Output Capacitance	$V_{DS} = -30V, V_{GS} = 0V, f = 1MHz$	C_{OSS}		80		pF
Reverse Transfer Capacitance	$V_{DS} = -30V, V_{GS} = 0V, f = 1MHz$	C_{RSS}		40		pF
Switching Characteristics ^{Note 4}						
Turn-On Delay Time	$V_{DD} = -30V, V_{GS} = -10V, I_D = -1A, R_{G(ext)} = 6\Omega$	$t_{D(ON)}$		10		ns
Turn-On Rise Time	$V_{DD} = -30V, V_{GS} = -10V, I_D = -1A, R_{G(ext)} = 6\Omega$	t_R		4		ns
Turn-Off Delay Time	$V_{DD} = -30V, V_{GS} = -10V, I_D = -1A, R_{G(ext)} = 6\Omega$	$t_{D(OFF)}$		32		ns
Turn-Off Fall Time	$V_{DD} = -30V, V_{GS} = -10V, I_D = -1A, R_{G(ext)} = 6\Omega$	t_F		3		ns
Total Gate Charge	$V_{DS} = -30V, V_{GS} = -10V, I_D = -2A$	Q_G		12		nC
Gate Source Charge	$V_{DS} = -30V, V_{GS} = -10V, I_D = -2A$	Q_{GS}		1.1		nC
Gate Drain Charge	$V_{DS} = -30V, V_{GS} = -10V, I_D = -2A$	Q_{GD}		2.7		nC
Drain-Source Diode Characteristics and Maximum Ratings						
Drain-Source Diode Forward Current ^{Note 2}		I_S			-2.5	A
Drain-Source Diode Forward Voltage ^{Note 3}	$V_{GS} = 0V, I_S = -1A$	V_{SD}			-1	V

Notes

- 1: Repetitive Rating: Pulse width limited by maximum junction temperature
- 2: Surface Mounted on FR4 Board, $t \leq 10$ sec.
- 3: Pulse Test: Pulse Width $\leq 300\mu s$, Duty Cycle $\leq 2\%$.
- 4: Guaranteed by design, not subject to production testing.

REFERENCE DATA ▲ TYPICAL DEVICE PERFORMANCE

Fig. 1 • Output Characteristics

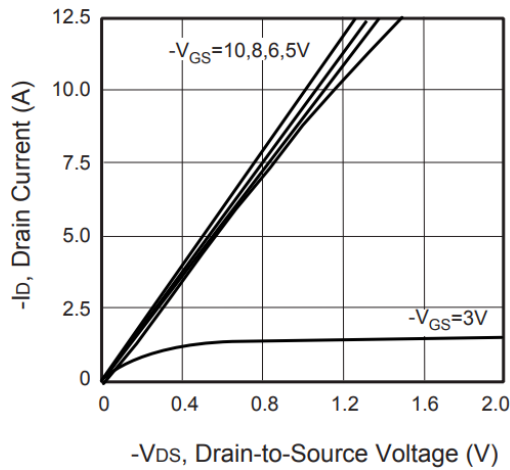


Fig. 2 • Transfer Characteristics

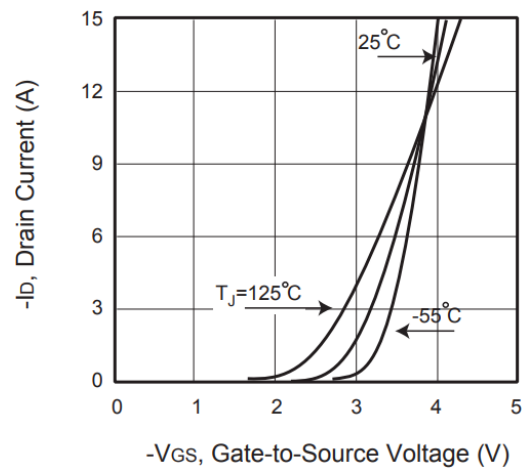


Fig. 3 • Capacitance

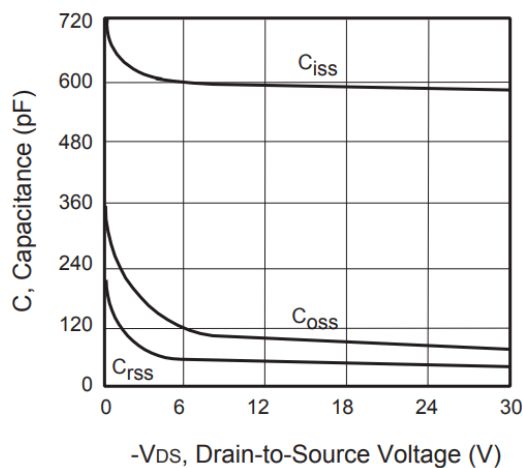


Fig. 4 • On-Resistance Variation with Temperature

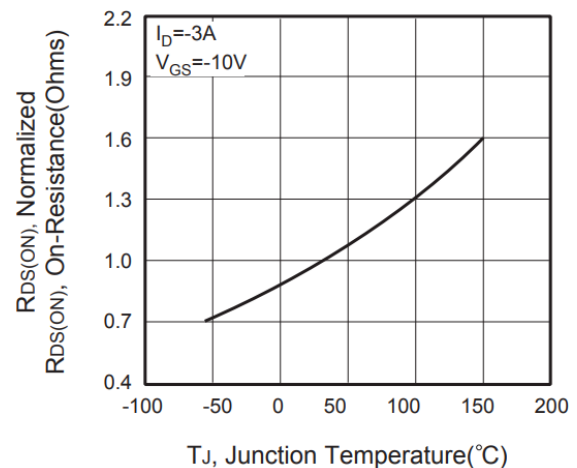


Fig. 5 • Gate Threshold Variation with Temperature

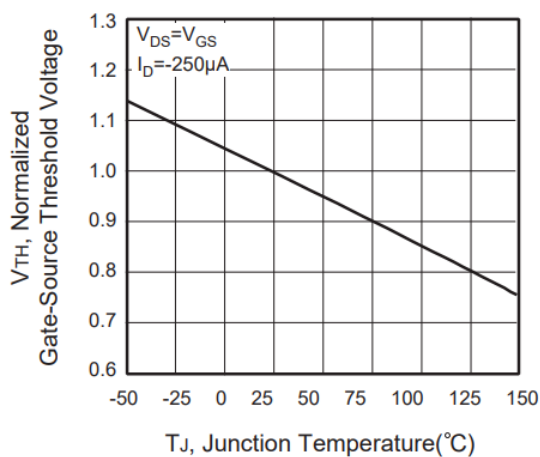
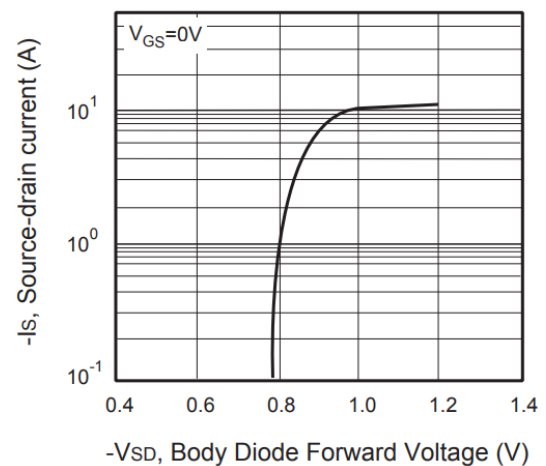


Fig. 6 • Body Diode Forward Voltage Variation with Source Current



REFERENCE DATA ▲ TYPICAL DEVICE PERFORMANCE

Fig. 7 • Gate Charge

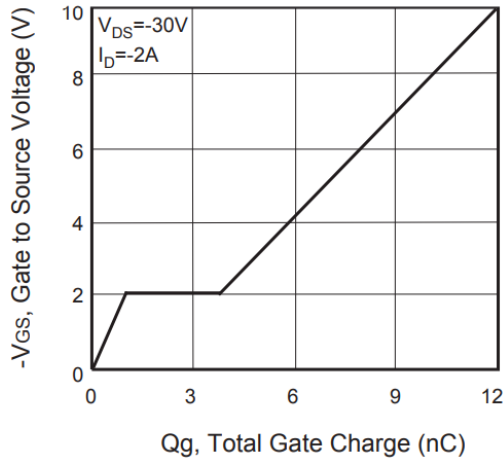


Fig. 8 • Maximum Safe Operating Area

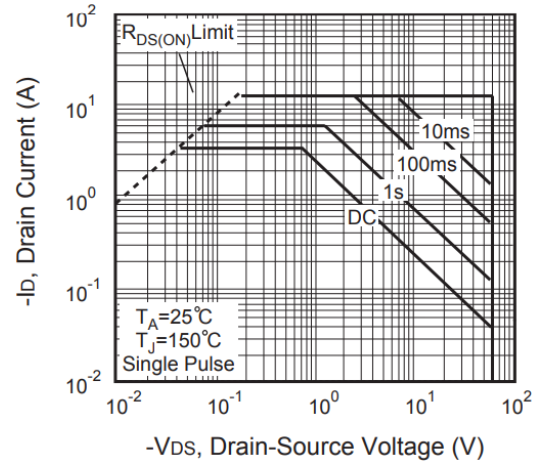


Fig. 9 • Breakdown Voltage Variation vs. Temperature

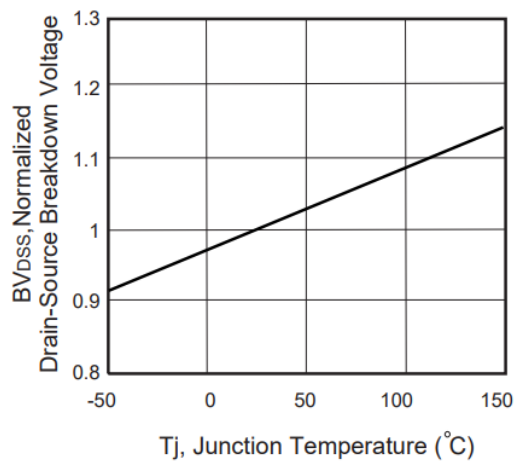


Fig. 10 • Switching Test Circuit

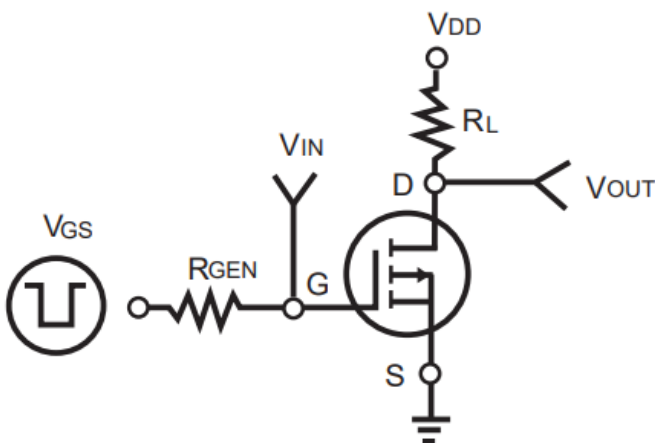
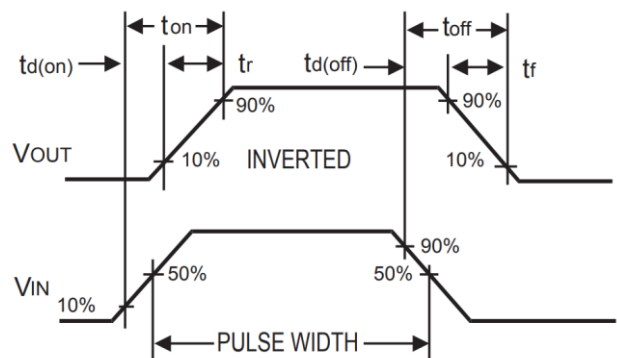
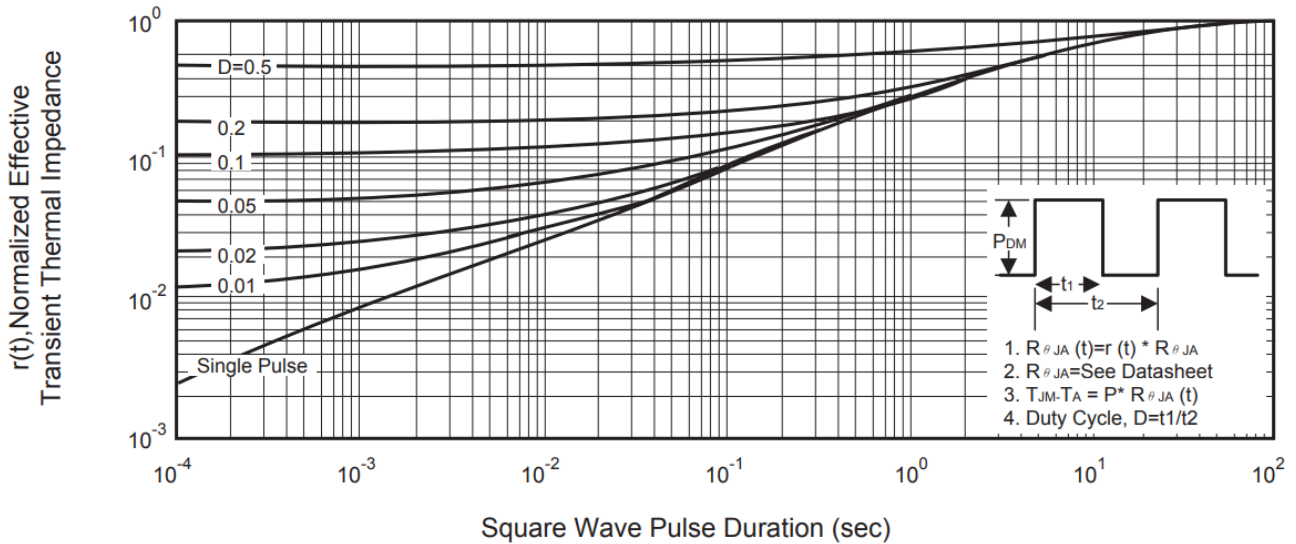


Fig. 11 • Switching Waveforms

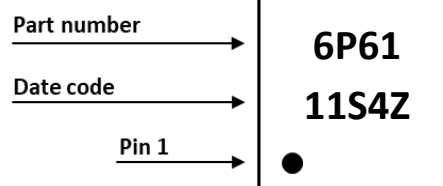


REFERENCE DATA ▲ TYPICAL DEVICE PERFORMANCE

Fig. 12 • Normalized Thermal Transient Impedance Curve



PART MARKING



DATE CODE

Example: 11S4Z



Coding list for „Day“

1	2	3	4	5	6	7	8	9	A
01	02	03	04	05	06	07	08	09	10
B	C	D	E	F	G	H	I	J	K
11	12	13	14	15	16	17	18	19	20
L	M	N	O	P	Q	R	S	T	U
21	22	23	24	25	26	27	28	29	30
V									
31									

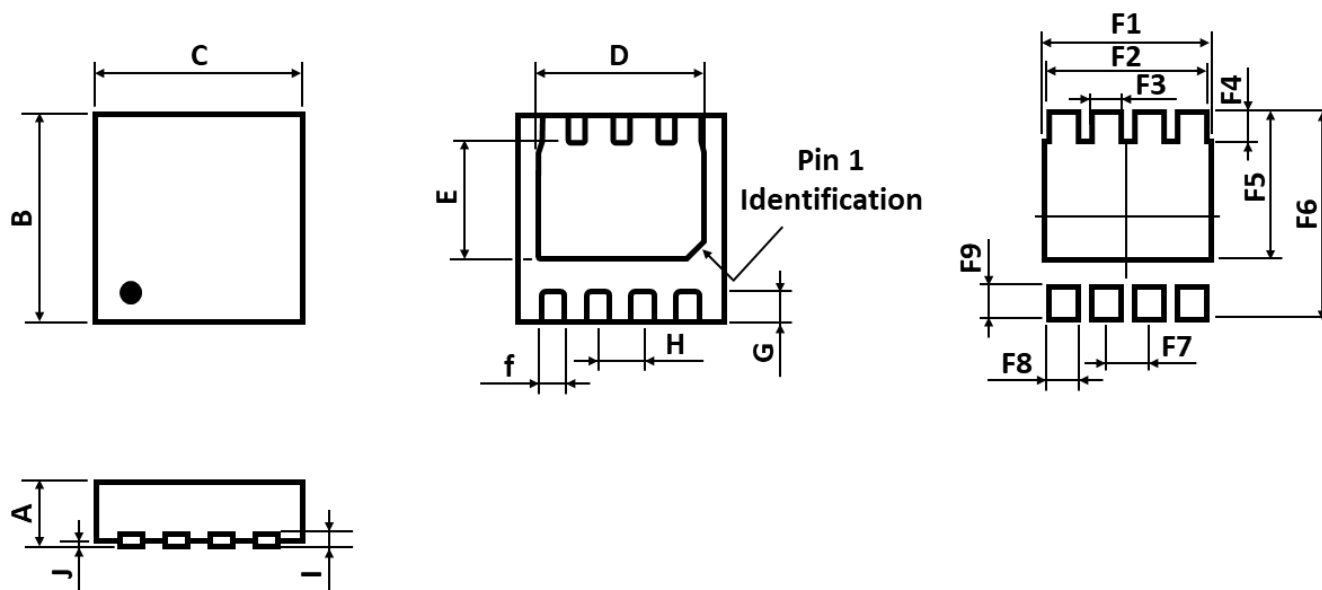
Coding list for „Month“

1	2	3	4	5	6
Jan	Feb	Mar	Apr	May	Jun
7	8	9	A	B	C
Jul	Aug	Sep	Oct	Nov	Dec

Coding list for „Year“

0	1	2	3	4
2020	2021	2022	2023	2024
5	6	7	8	9
2025	2026	2027	2028	2029

PACKAGE OUTLINE AND RECOMMENDED PAD LAYOUT



Sym	Millimeters (Min.)	Millimeters (Typ.)	Millimeters (Max.)
A	0.700	-	0.850
B	2.900	-	3.100
C	2.900	-	3.100
D	2.350	-	2.490
E	1.650	-	1.750

Sym	Millimeters (Min.)	Millimeters (Typ.)	Millimeters (Max.)
f	0.300	-	0.400
G	0.350	-	0.480
H	0.650 (BSC)		
I	0.203 (REF)		
J	0.000	-	0.050

Sym	Millimeters (Min.)	Millimeters (Typ.)	Millimeters (Max.)
F1	-	2.500	-
F2	-	2.400	-
F3	-	0.450	-
F4	-	0.450	-
F5	-	2.200	-

Sym	Millimeters (Min.)	Millimeters (Typ.)	Millimeters (Max.)
F6	-	3.100	-
F7	-	0.650	-
F8	-	0.450	-
F9	-	0.500	-

Notes: 1. The suggested land pattern dimensions have been provided for reference only.
2. For further information, please reference document IPC-7351A.

ORDERING INFORMATION

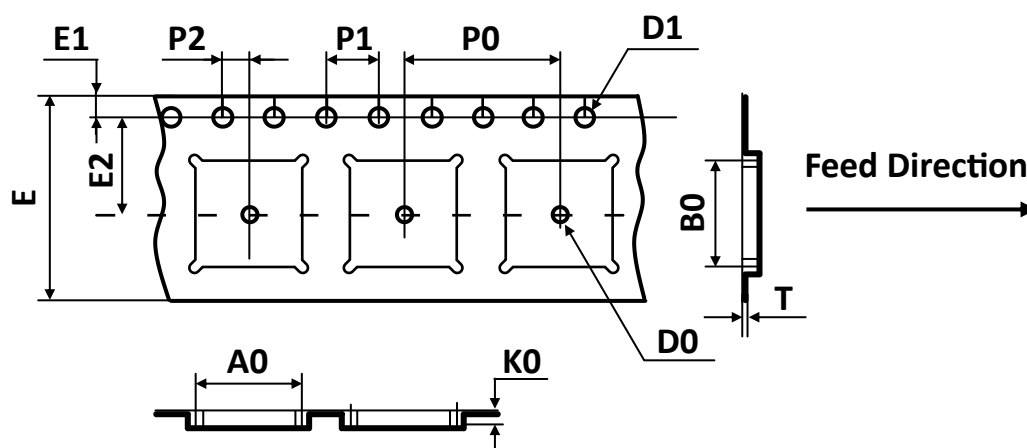
Part Number	Package	Packing	Reel Qty.	Inner Box Qty.	Outer Box Qty.
CEC6P61	DFN 3x3	Reel	3,000pcs	6,000pcs	48,000pcs

REEL DIMENSIONS ▲ All dimensions in mm



Tape Size	Reel Size	M	N	T	H	K	S
12mm	Ø330	Ø330.00 ±2.00	Ø100.00 ±0.50	2.20 ±0.20	20.00 ±1.00	13.20 ±0.20	3.00 ±1.00

TAPE DIMENSIONS ▲ All dimensions in mm



Package	A0	B0	K0	D0	D1	E	E1	E2	P0	P1	P2	T
DFN 3x3	3.30 ±0.10	3.30 ±0.10	1.10 ±0.15	1.50 ±0.10	1.50 ±0.10	12.00 ±0.10	1.75 ±0.10	5.50 ±0.10	8.00 ±0.10	4.00 ±0.10	2.00 ±0.05	0.23 ±0.02

Note: All dimensions meet EIA-481-D requirements.

RECOMMENDED REFLOW SOLDERING PROFILE



Recommended reflow soldering conditions ▲ Refer to JEDEC J-STD-020E

Profile Features		Sn-Pb Eutetic Assembly	Pb-Free Assembly
Preheat temperature min.	$T_{s \min}$	100 °C	150 °C
Preheat temperature max.	$T_{s \max}$	150 °C	200 °C
Preheat time t_s from $T_{s \min}$ to $T_{s \max}$	t_s	120 seconds	120 seconds
Ramp-up rate (T_L to T_p)		max. 3 °C/second	max. 3 °C/second
Liquidous temperature	T_L	183 °C	217 °C
Time t_L maintained above T_L	t_L	150 seconds max.	150 seconds max.
Peak package body temperature	T_p	235°C	260°C
Timeframe of within 5°C below and up to max actual peak body temperature	t_p	20 seconds max.	30 seconds max.
Ramp-down rate (T_L to T_p)		max. 6 °C/second	max. 6 °C/second
Time 25°C to peak temperature		max. 6 minutes	max. 8 minutes

REVISION TABLE

Revision	Date	Status	Notes
001	30/09/2022	Initial release	Initial publication

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